Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

## 2SK2916

# DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain–source ON resistance :  $R_{DS (ON)} = 0.35 \Omega \text{ (typ.)}$ • High forward transfer admittance :  $|Y_{fs}| = 11 \text{ S (typ.)}$ • Low leakage current :  $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 500 \text{ V)}$ 

• Enhancement mode :  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

#### Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	500	V
Drain–gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	500	V
Gate-source voltage		$V_{GSS}$	±30	٧
Drain current	DC (Note 1)	I <sub>D</sub>	14	Α
	Pulse (Note 1)	I <sub>DP</sub>	56	Α
Drain power dissipatio	n (Tc = 25°C)	$P_{D}$	80	W
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	795	mJ
Avalanche current		I <sub>AR</sub>	14	А
Repetitive avalanche e	energy (Note 3)	E <sub>AR</sub>	8	mJ
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C

Weight: 5.8 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.56	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	41.6	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = 90 V, starting  $T_{ch}$  = 25°C, L = 6.9 mH,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = 14 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



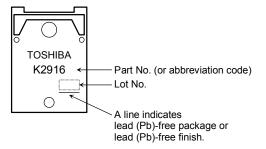
## **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V		_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I <sub>G</sub> = ±10 μA, V <sub>DS</sub> = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	500	_	_	V
Gate threshold v	/oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7.0 A	_	0.35	0.4	Ω
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 7.0 A	6	11	_	S
Input capacitano	ce	C <sub>iss</sub>		_	2600	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	280	_	pF
Output capacitance		Coss			880	_	
Switching time	Rise time	t <sub>r</sub>	V <sub>GS</sub> <sub>0V</sub> I <sub>D</sub> =7.0A <sub>O</sub> V <sub>OUT</sub> R <sub>L</sub> =30Ω	_	50	_	
	Turn-on time	t <sub>on</sub>		_	85	_	20
	Fall time	t <sub>f</sub>		_	65	_	- ns
	Turn-off time	t <sub>off</sub>	$V_{DD} = 210V$ Duty \leq 1\%, t <sub>w</sub> = 10\mu s	_	260	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	58	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 14 \text{ A}$		36	_	nC
Gate-drain ("miller") Charge		Q <sub>gd</sub>			22	_	

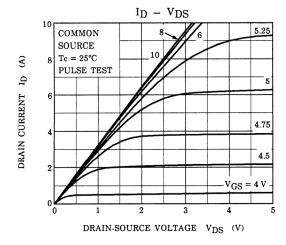
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

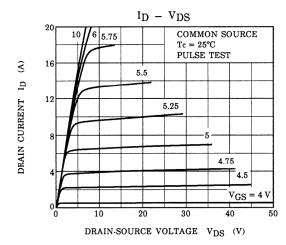
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	14	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	56	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 14 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 14 A, V <sub>GS</sub> = 0 V		400	-	ns
Reverse recovery charge	Q <sub>rr</sub>	dl <sub>DR</sub> / dt = 100 Å / μs	_	4.3	_	μC

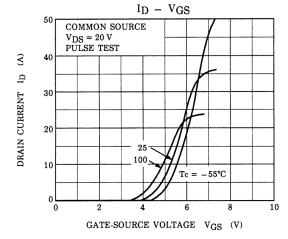
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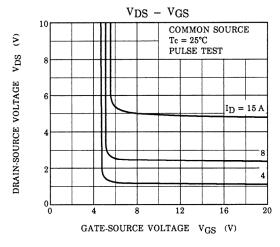


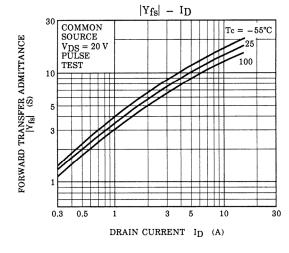
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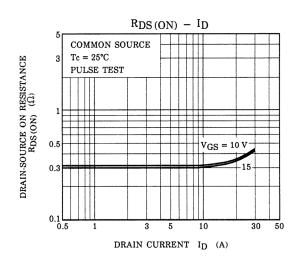


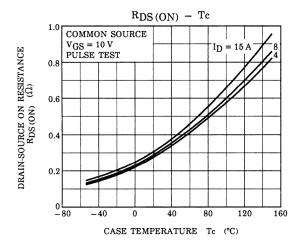


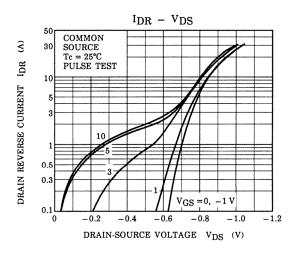


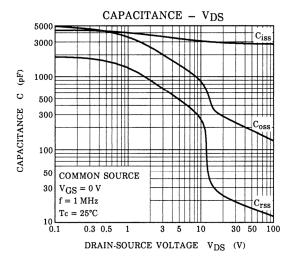


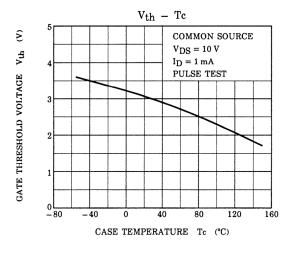


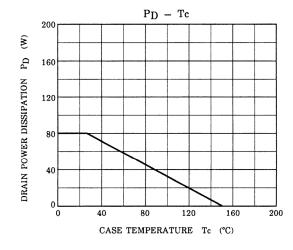


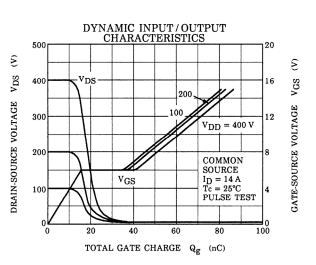




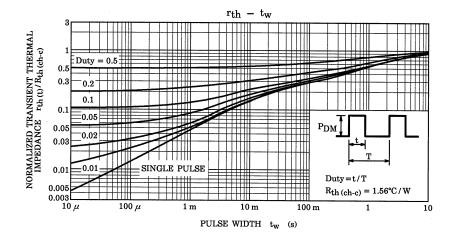


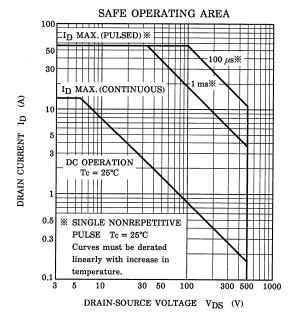


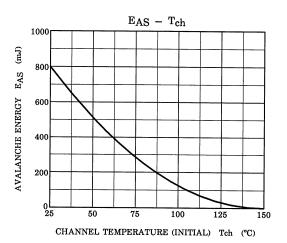


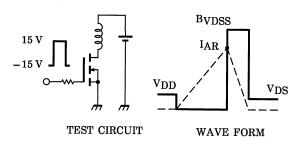


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$$\begin{aligned} &RG = 25~\Omega \\ &V_{DD} = 90~V,~L = 6.9~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right)$$

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